L Number	Hits	Search Text	I DD	Time chame
_ L Number	5	6261919.pn. 6340604.pn. 4967146.pn.	DB USPAT	Time stamp 2003/02/24 14:12
_	,	6228684.pn. 5838361.pn.	USPAI	2003/02/24 14:12
_	3	6228676.pn. 4607219.pn. 6358776.pn.	USPAT	2002/09/25 12:13
_	11	"911924"	USPAT;	2003/02/24 14:19
		311321	US-PGPUB;	2003/02/24 14.19
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	7	(US-4607219-\$ or US-6358776-\$ or	USPĀT;	2002/09/25 14:12
		US-4967146-\$ or US-5838361-\$ or	US-PGPUB	1
		US-6261919-\$ or US-6228676-\$).did. or		
		(US-20020016013-\$).did.		
_	2	((US-4607219-\$ or US-6358776-\$ or	USPAT	2002/09/25 14:12
		US-4967146-\$ or US-5838361-\$ or	}	
		US-6261919-\$ or US-6228676-\$).did. or		
		(US-20020016013-\$).did.) and position	}	
-	1	jp11316209	USPAT;	2003/02/24 14:40
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
-	7690	(TAKEHARA or NAKAGAWA) and (resin or mark)	USPAT;	2003/02/24 14:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	224	((77)	IBM_TDB	0000/00/01
_	774	((TAKEHARA or NAKAGAWA) and (resin or mark)) and (resin or mark).clm.	USPAT	2003/02/24 14:43
	8	, , , , , , , , , , , , , , , , , , , ,	USPAT	2002/02/24 14:42
_	8	(((TAKEHARA or NAKAGAWA) and (resin or	USPAT	2003/02/24 14:43
		<pre>mark)) and (resin or mark).clm.) and test\$3.clm.</pre>		
_	3	("5903044" "6165815" "6180435").PN.	USPAT	2003/02/24 14:52
	31322	seal\$3 and mark\$3 and front and (back or	USPAT	2003/02/24 14:32
	31322	opposite)	OSTAI	2003/02/23 10.13
_	130	(seal\$3 and mark\$3 and front and (back or	USPAT	2003/02/25 10:20
		opposite)).clm.	001111	2003,02,23 10.20
_	15	((seal\$3 and mark\$3 and front and (back or	USPAT	2003/02/25 10:20
		opposite)).clm.) and (resin or		
		encapsulant).clm.		
_	304	(seal\$3 and mark\$3 and front and (back or	USPAT	2003/02/25 10:21
		opposite)) and (mark\$3 and front and (back	}	
		or opposite)).clm.		
_	5	(((seal\$3 and mark\$3 and front and (back	USPAT	2003/02/25 10:21
		or opposite)) and (mark\$3 and front and		
		(back or opposite)).clm.) and		
		(semiconductor or chip)) and (resin or		
		encapsulant).clm.		
_	24	((seal\$3 and mark\$3 and front and (back or	USPAT	2003/02/25 10:32
		opposite)) and (mark\$3 and front and (back		
		or opposite)).clm.) and (semiconductor or		
	_	chip)	HODE	0000 /00 /05 10 00
_	5	("4418467" "5972234" "6004405"	USPAT	2003/02/25 10:28
		"6063695" "6066513").PN.	HODAE	2002/02/25 10:30
_	1101	6261919.URPN. (seal\$3 and front and (back or	USPAT USPAT	2003/02/25 10:30
_	1101	opposite)) and backside	USPAI	2003/02/25 10:32
_	55	opposite); and backside ((seal\$3 and mark\$3 and front and (back or	USPAT	2003/02/25 10:32
	33	opposite)) and backside) and mark\$3.clm.	USEAL	2003/02/23 10:32
_	17	(((seal\$3 and mark\$3 and front and (back	USPAT	2003/02/25 10:44
		or opposite)) and backside) and	73171	2003/02/23 10.44
		mark\$3.clm.) and (semiconductor or chip or		
		wafer)		
_	5	("4214249" "4401992" "5061341"	USPAT	2003/02/25 10:42
		"6162651" "6181017").PN.	33171	2000,02,20 10.42
_	1	"5688573".PN.	USPAT	2003/02/25 10:42
_	1	6162651.URPN.	USPAT	2003/02/25 10:42
_	Ō	6432796.URPN.	USPAT	2003/02/25 10:43
_	20	438/401 and resin	USPAT	2003/02/25 10:44
<u> </u>				

•				
-	1447	(438/113 or 438/401 or 347/262 or 324/765	USPAT	2003/02/25 11:03
		or 438/15 or 438/107 or 257/787 or 361/760		
).ccls. and (resin or encapsula\$4 or		
		seal\$3).clm.		
-	439	((438/113 or 438/401 or 347/262 or 324/765	USPAT	2003/02/25 11:04
		or 438/15 or 438/107 or 257/787 or 361/760	į	
).ccls. and (resin or encapsula\$4 or		ł
1		seal\$3).clm.) and (back or backside or		
		opposite).clm.		
-	90	(((438/113 or 438/401 or 347/262 or	USPAT	2003/02/25 11:04
		324/765 or 438/15 or 438/107 or 257/787 or		
		361/760).ccls. and (resin or encapsula\$4		
		or seal\$3).clm.) and (back or backside or		
		opposite).clm.) and (mark\$3 or scribing or		
		enscribing)		
-	35	"190" and (chip or wafer)	USPAT	2003/02/25 11:05
-	85	((((438/113 or 438/401 or 347/262 or	USPAT	2003/02/25 11:05
		324/765 or 438/15 or 438/107 or 257/787 or		
		361/760).ccls. and (resin or encapsula\$4		1
		or seal\$3).clm.) and (back or backside or		
		opposite).clm.) and (mark\$3 or scribing or		
		enscribing)) and (chip or wafer)		
-	75	((((438/113 or 438/401 or 347/262 or	USPAT	2003/02/25 11:05
1	1	324/765 or 438/15 or 438/107 or 257/787 or		
	1	361/760).ccls. and (resin or encapsula\$4		
		or seal\$3).clm.) and (back or backside or		
	1	opposite).clm.) and (mark\$3 or scribing or		
		enscribing)) and (chip or wafer).clm.		
-	52	, , , , , , , , , , , , , , , , , , , ,	USPAT	2003/02/25 11:05
		324/765 or 438/15 or 438/107 or 257/787 or		
		361/760).ccls. and (resin or encapsula\$4	}	
		or seal\$3).clm.) and (back or backside or		
1	1	opposite).clm.) and (mark\$3 or scribing or		
		enscribing)) and (chip or wafer).clm.) and		
		seal\$3		
-	35	(((((438/113 or 438/401 or 347/262 or	USPAT	2003/02/25 11:05
		324/765 or 438/15 or 438/107 or 257/787 or		
		361/760).ccls. and (resin or encapsula\$4		
		or seal\$3).clm.) and (back or backside or		
		opposite).clm.) and (mark\$3 or scribing or		
		enscribing)) and (chip or wafer).clm.) and		
		seal\$3.clm.		